



Material Content Data Sheet



Sales Product Name				BSC018N04LS G		Issued		4. October 2018	
MA#				MA001831312					
Package				PG-TDSON-8-1		Weight*		121.96 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.071	3.34	3.34	33382	33382	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93		
	non noble metal	iron	7439-89-6	0.038	0.03		310		
wire	non noble metal	copper	7440-50-8	37.762	30.94	30.98	309625	310028	
	non noble metal	copper	7440-50-8	0.031	0.03	0.03	255	255	
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		659		
	plastics	epoxy resin	-	5.709	4.68		46807		
leadfinish	inorganic material	silicondioxide	60676-86-0	34.412	28.22	32.97	282162	329628	
	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11903	11903	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1357	1357	
solder	non noble metal	tin	7440-31-5	0.066	0.05		538		
	noble metal	silver	7440-22-4	0.082	0.07		673		
heatspreader	non noble metal	lead	7439-92-1	3.135	2.57	2.69	25707	26918	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		93		
	non noble metal	copper	7440-50-8	11.320	9.28	9.29	92818	92939	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	iron	7439-89-6	0.022	0.02		183		
heat sink CLIP	noble metal	silver	7440-22-4	1.289	1.06		10573		
	non noble metal	copper	7440-50-8	22.292	18.28	19.37	182779	193590	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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